

# Final Product/Process Change Notification Document #: FPCN25188Z Issue Date: 17 Mar 2023

Title of Change:	Assembly and Final Test Site Transfer from onsemi, Vietnam to JCET, China.		
Proposed Changed Material First Ship Date:	24 Sep 2023 or earlier if approved by customer		
Current Material Last Order Date:	N/A Orders received after the Current Material Last Order Date expiration are to be considered as orders for new changed material as described in this PCN. Orders for current (unchanged) material after this date will be per mutual agreement and current material inventory availability.		
Current Material Last Delivery Date:	N/A The Current Material Last Delivery Date may be subject to change based on build and depletion of the current (unchanged) material inventory		
Product Category:	Active components – Integrated circuits		
Contact information:	Contact your local onsemi Sales Office or Zihan.Shang@onsemi.com		
PCN Samples Contact:	Contact your local onsemi Sales Office to place sample order. Sample requests are to be submitted no later than 45 days after publication of this change notification. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.		
Sample Availability Date:	28 Mar 2023		
PPAP Availability Date:	12 May 2023		
Additional Reliability Data:	Contact your local onsemi Sales Office or MohdAzizi.Azman@onsemi.com		
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. The change will be implemented at 'Proposed Change Material First Ship Date' in compliance to J-STD-46 or ZVEI, or earlier upon customer approval, or per our signed agreements. onsemi will consider this proposed change and it's conditions acceptable, unless an inquiry is made in writing within 45 days of delivery of this notice. To do so, contact <a href="mailto:PCN.Support@onsemi.com">PCN.Support@onsemi.com</a> .		
Change Category			
Category	Type of Change		
Test Flow	Move of all or part of electrical wafer test and/or final test to a different location/site/subcontractor		
Equipment	Change in final test equipment type that uses a different technology, Production from a new equipment/tool which uses the same basic technology (replacement equipment or extension of existing equipment pool) without change of process.		
Process - Assembly	Move of all or part of assembly to a different location/site/subcontractor., Change of mold compound, Die attach material		

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### **Description and Purpose:**

Transfer of assembly and final test manufacturing from onsemi, Vietnam to JCET, China. See details of change in chart below.

Purpose of change is capacity improvement.

	From	То
Assembly Site	onsemi, Vietnam	JCET, China
Die Attach	Pb95Sn5	92.5%Pb,2.5%Sn,5%Ag
Mold Compound	G700HF	CEL-9240HF10
Final Test Site	onsemi, Vietnam	JCET, China
Final Test Equipment	Tesec 881A	STS8203

There is no product marking change as a result of this change

Reason / Motivation for Change:	Capacity improvement		
Anticipated impact on fit, form, function, reliability, product safety or manufacturability:	The device has been qualified and validated based on the same Product Specification. The device has successfully passed the qualification tests. Potential impacts can be identified, but due to testing performed by onsemi in relation to the PCN, associated risks are verified and excluded.  No anticipated impacts.		
Sites Affected:			
onsemi Sites		External Foundry/Subcon Sites	
onsemi Vietnam		JCET, China	

Marking of Parts/	Traceability of
Change:	

Traceable by Date Code

**Reliability Data Summary:** 

**QV DEVICE NAME: NCV8401ADTRKG** 

RMS: S85946, S86124 PACKAGE: DPAK

Test	Specification	Condition	Interval	Results
Early Life Failure Rate	JESD22-A108	Ta=125°C, 100 % max rated Vcc	48 hrs	0/1200
High Temperature Reverse Bias	JESD22-A108	Ta=150°C, 100% max rated V	1008 hrs	0/231
High Temperature Operating Life	JESD22-A108	Ta=125°C, 100 % max rated Vcc	1008 hrs	0/231
High Temperature Storage Life	JESD22-A103	Ta= 150°C	1008 hrs	0/231
Preconditioning	J-STD-020 JESD-A113	MSL 1 @ 260 °C, Pre IOL, TC, uHAST, HAST, PTC for surface mount pkgs only		0/1155
Intermittent Operating Life	MIL-STD-750 (M1037) AEC-Q101	Ta=+25°C, delta Tj=100°C On/off = 2 min	15000 cyc	0/231
Power Temperature Cycling	JESD22-A105	-40°C to 125°C	1000 cyc	0/231
Temperature Cycling	JESD22-A104	Ta= -55°C to +150°C, mount on board	1000 cyc	0/231
Highly Accelerated Stress Test	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs	0/231

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Unbiased Highly Accelerated Stress Test	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/231
Resistance to Solder Heat	JESD22- B106	Ta = 265°C, 10 sec Required for through hole devices only		0/90
Solderability	JSTD002	Ta = 245°C, 5 sec		0/45
Physical Dimensions	JESD22-B120			0/30

**QV DEVICE NAME: NCV8406ADTRKG** 

RMS: S86020 PACKAGE: DPAK

Test	Specification	Condition	Interval	Results
High Temperature Storage Life	JESD22-A103	Ta= 150°C	1008 hrs	0/231
Preconditioning	J-STD-020 JESD-A113	MSL 1 @ 260 °C, Pre TC, uHAST for surface mount pkgs only		0/462
Temperature Cycling	JESD22-A104	Ta= -55°C to +150°C, mount on board	1000 cyc	0/231
Unbiased Highly Accelerated Stress Test	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/231
Resistance to Solder Heat	JESD22- B106	Ta = 265°C, 10 sec Required for through hole devices only		0/90

Note: AEC\_1pager is attached.

To view attachments:

- 1. Download pdf copy of the PCN to your computer
- 2. Open the downloaded pdf copy of the PCN
- 3. Click on the paper clip icon available on the menu provided in the left/bottom portion of the screen to reveal the Attachment field
- 4. Then click on the attached file.

## **Electrical Characteristics Summary:**

Electrical characteristics are not impacted.

#### List of Affected Parts:

**Note:** Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal**.

Current Part Number	New Part Number	Qualification Vehicle	
NCV8401BDTRKG	N/A	NCV8401ADTRKG	
NCV8403BDTRKG	N/A	NCV8401ADTRKG	
NCV8405BDTRKG	N/A	NCV8406ADTRKG	
NCV8406BDTRKG	N/A	NCV8406ADTRKG	
NCV8408BDTRKG	N/A	NCV8401ADTRKG	
NCV8411DTRKG	N/A	NCV8401ADTRKG	
NCV8413DTRKG	N/A	NCV8401ADTRKG	
NCV8415DTRKG	N/A	NCV8401ADTRKG	

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## **Appendix A: Changed Products**

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DIKG: DIGI-KEY

Product	Customer Part Number	Qualification Vehicle	New Part Number	Replacement Supplier
NCV8401BDTRKG		NCV8401ADTRKG		
NCV8406BDTRKG		NCV8406ADTRKG		
NCV8408BDTRKG		NCV8401ADTRKG		
NCV8411DTRKG		NCV8401ADTRKG		
NCV8413DTRKG		NCV8401ADTRKG		
NCV8403BDTRKG		NCV8401ADTRKG		